

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	63602	leadframe (lead adj frame)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/24 12:40
L2	1874717	lead 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/24 12:33
L3	54126	2 with (protrude protruding protruded protrusion width wide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/24 12:39
L4	11940	(die chip ic (integrated adj circuit) semiconductor) same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/24 12:40
L5	11940	4 same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/24 12:40
L6	3397	4 same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/24 12:41
L7	2107	(package packaging packaged) and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/24 12:43
L8	412180	(end tip portion middle section) with 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/24 12:43

L9	1583	7 and "8"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/24 12:44
L10	1745	7 and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/24 12:44